

ABSTRACT

5 A die mold machine for molding a plurality of semiconductor assemblies
on multiple substrate/leadframes includes a plurality of die mold layers stacked
vertically one above the other to form a plurality of die mold sections. The top die
mold layer has at least one aperture or die hall in the top most die layer and
apertures or die halls in the in-between layers for passing molding compound
which flows through the die hall in the top layer down through the die halls or
10 apertures between the die mold layers into the die mold sections for molding
semiconductor assemblies on said substrate/leadframes between said die mold
layers.